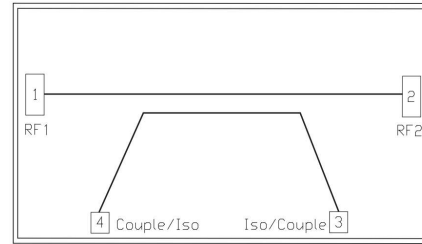


### Performance

- Frequency: 8~12GHz
- Coupling: 10dB
- Coupling Flatness: 1dB
- Chip size: 2.0\*1.3\*0.1mm

### Function Diagram

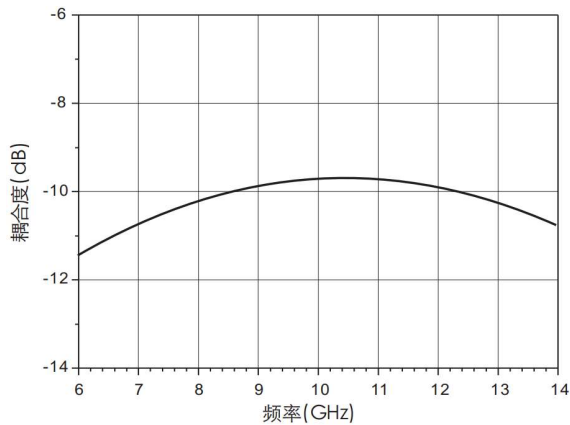


### Electrical Specifications (Ta=+25°C, 50Ω system)

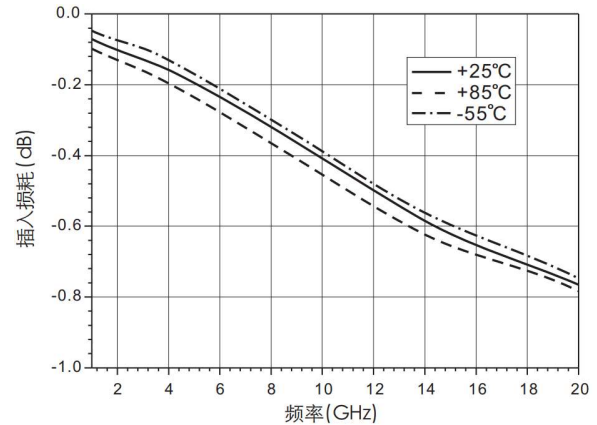
Parameter	Min	Typical	Max	Unit
Frequency Range	8~12			GHz
Coupling	9.6	10	10.3	
Insertion Loss	0.3	0.4	0.6	dB
Input Return loss	20	21	-	dB
Thru Output Return loss	24	30	-	dB
Coupling Output Return loss	26	30	-	dB

### Test Curves (Die chip + Bonding line test)

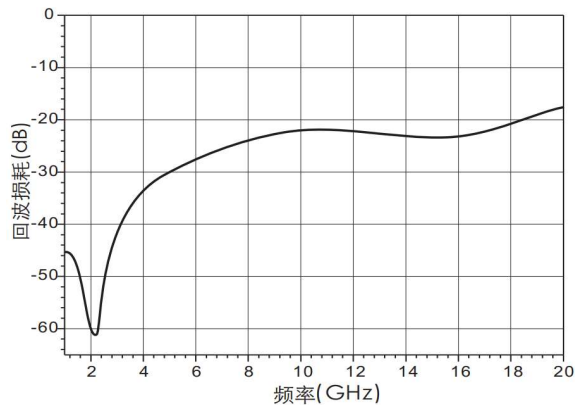
Coupling vs. Freq



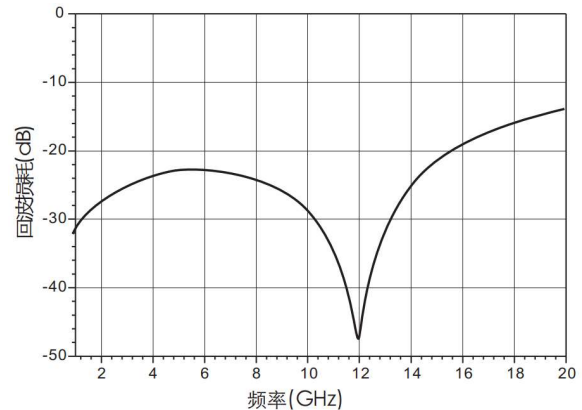
Insertion loss vs. Freq



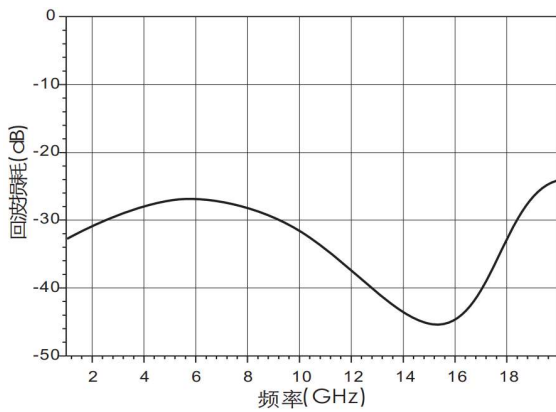
Input Return Loss vs. Freq



Thru output Return loss vs. Freq

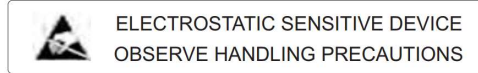


Coupling Output Return Loss

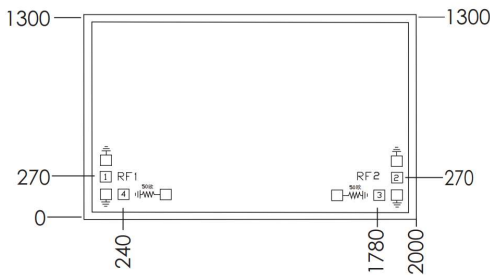


**Absolute Rating**

Storage Temperature	-65~+150°C
Operating Temperature	-55~+125°C
Max Input Power	5W
Static Protection (HBM)	Class 1A



**Outline Size**



**Note:**

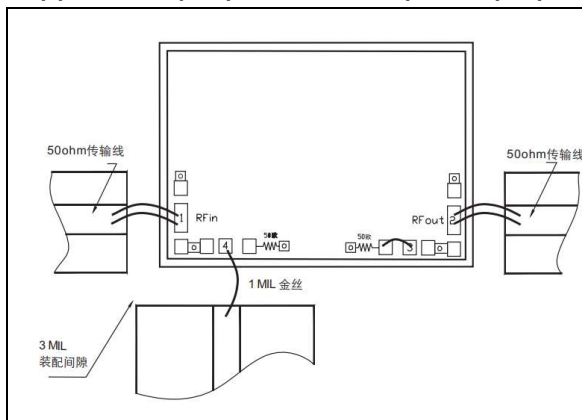
Unit: um

1. Bottom side is gold plated
2. Bottom side is GND
3. Bonding pads is gold plated, size: 100\*100(um)
4. Don't bonding on thru holds
5. Tolerance: ±50um

**Bonding Pads Definition**

Number	Symbol	Description
1	RFin	RF input port, 50ohm
2	RFout	RF output port, 50 ohm
3,4	Couple/ISO	Choose either one as couple output port, another port connect to 50Ω resistor pad
5,6	Load	50Ω resistor pad

**Application (Chip left side couple output)**



**Application (Chip right side couple output)**

